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## GenX3<sup>™</sup> 1200V IGBT w/ Diode

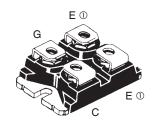
## IXGN82N120C3H1

High-Speed PT IGBT for 20-50 kHz Switching



<b>V</b> <sub>CES</sub>	=	1200\
C110	=	58A
V <sub>CE(sat)</sub>	<u> </u>	3.9V

# SOT-227B, miniBLOC **₹1** E153432



G = Gate, C = Collector, E = Emitter

① either emitter terminal can be used as
Main or Kelvin Emitter

Symbol	<b>Test Conditions</b>		Maximum Ratings			
V <sub>CES</sub>	T <sub>J</sub> = 25°C to 150	°C	1200	V		
V <sub>CGR</sub>	$T_{J} = 25^{\circ} \text{C to } 150^{\circ}$	$^{\circ}$ C, R <sub>GE</sub> = 1M $\Omega$	1200	V		
V <sub>GES</sub>	Continuous		±20	V		
V <sub>GEM</sub>	Transient		±30	V		
I <sub>C25</sub>	T <sub>C</sub> = 25°C		130	A		
I <sub>C110</sub>	$T_{c} = 110^{\circ}C$		58	Α		
I <sub>F110</sub>	$T_{c}^{\circ} = 110^{\circ}C$		42	Α		
I <sub>CM</sub>	$T_{\rm C}^{\circ} = 25^{\circ} \text{C}, 1 \text{ms}$		500	Α		
SSOA	$V_{GE} = 15V, T_{VJ} = 12$	$25^{\circ}$ C, $R_{g} = 3\Omega$	I <sub>CM</sub> = 164	A		
(RBSOA)	Clamped Inductive Load		$V_{CE} \le V_{CES}$			
P <sub>c</sub>	T <sub>C</sub> = 25°C		595	W		
T <sub>J</sub>			-55 +150	°C		
$T_{JM}$			150	°C		
T <sub>stg</sub>			-55 +150	°C		
V <sub>ISOL</sub>	50/60Hz	t = 1min	2500	V~		
1002	$I_{ISOL} \leq 1 mA$	t = 1s	3000	V~		
M <sub>d</sub>	Mounting Torque		1.5/13	Nm/lb.in.		
<b>-</b>	Terminal Connection Torque		1.3/11.5	Nm/lb.in.		
Weight			30	g		

#### **Features**

- Optimized for Low Switching Losses
- Square RBSOA
- High Current Capability
- Isolation Voltage 2500 V~
- Anti-Parallel Ultra Fast Diode
- International Standard Package

#### **Advantages**

- High Power Density
- Low Gate Drive Requirement

#### 

CES	$V_{CE} = V_{CES}$ , $V_{GE} = 0V$ , Note 1 $T_{J} = 125^{\circ}C$		50 μA 6 mA
I <sub>GES</sub>	$V_{CE} = 0V, V_{GE} = \pm 20V$		±200 nA
V <sub>CE(sat)</sub>	I <sub>C</sub> = 82A, V <sub>GE</sub> = 15V, Note 2	3.3	3.9 \

#### **Applications**

- Power Inverters
- UPS
- SMPS
- PFC Circuits
- Welding Machines
- Lamp Ballasts



Symbol	•			
$(T_J = 25^{\circ}C, l)$	Unless Otherwise Specified)	Min.	Тур.	Max.
$\mathbf{g}_{fs}$	$I_{\rm C}=60$ A, $V_{\rm CE}=10$ V, Note 2	38	62	S
C <sub>ies</sub>			7900	pF
C <sub>oes</sub>	$V_{CE} = 25V, V_{GE} = 0V, f = 1 MHz$		685	pF
C <sub>res</sub>			197	pF
Q <sub>g(on)</sub>			340	nC
$\mathbf{Q}_{ge}$	$I_{\rm C}=82{\rm A},V_{\rm GE}=15{\rm V},V_{\rm CE}=0.5\bullet V_{\rm CES}$		55	nC
Q <sub>gc</sub>			145	nC
t <sub>d(on)</sub>			30	ns
t <sub>ri</sub>	Inductive load, T <sub>J</sub> = 25°C		77	ns
E <sub>on</sub>	$I_{\rm C}=82A,V_{\rm GE}=15V$		5.0	mJ
t <sub>d(off)</sub>	$V_{CE} = 0.5 \cdot V_{CES}, R_{G} = 2\Omega$		194	ns
t <sub>fi</sub>	Note 3		100	ns
E <sub>off</sub>			2.5	5.0 mJ
t <sub>d(on)</sub>			32	ns
t <sub>ri</sub>	Inductive load, T <sub>J</sub> = 125°C		80	ns
E <sub>on</sub>	$I_{\rm C} = 82A, V_{\rm GE} = 15V$		6.8	mJ
t <sub>d(off)</sub>	$V_{CE} = 0.5 \cdot V_{CES}, R_G = 2\Omega$		230	ns
t <sub>fi</sub>	Note 3		270	ns
E <sub>off</sub>			4.0	mJ
R <sub>thJC</sub>				0.21 °C/W
R <sub>thCK</sub>			0.05	°C/W

### SOT-227B miniBLOC (IXGN) INCHES MIN MAX 31.88 8.20 4.29 MAX 1.240 .307 31.50 7.80 4.09 .161 .161 4.09 .169 4.09 14.91 30.12 38.00 11.68 8.92 1.186 1.496 .460 .481

9.60 0.84

26.90 4.42

4.85 25.07

12.60 25.15 1.98

4.95

26.54 3.94

-0.05

.496 .990 .078

.195

1.045

1.001 .084

.235 1.059

.191 .987

.004

#### Reverse Diode (FRED)

Symbol Test Conditions (T, = 25°C, Unless Otherwise Specified)			Characteristic Values Min.   Typ.   Max.			
<b>V</b> <sub>E</sub>	$I_F = 60A$ , $V_{GF} = 0V$ , Note 1			-7/-	2.5	
F	F GE GE	$T_J = 150^{\circ}C$		1.4	1.8	V
I <sub>RM</sub>	$\begin{cases} I_{F} = 60A, V_{GE} = 0V, \\ -di_{F}/dt = 200A/\mu s, V_{R} = 300V \end{cases}$	T <sub>J</sub> = 100°C		8.3		Α
t <sub>rr</sub>	$\int -di_{F}/dt = 200A/\mu s, V_{R} = 300V$			140		ns
R <sub>thJC</sub>					0.42 °C	C/W

#### Notes:

- 1. Part must be heatsunk for high-temp Ices measurement.
- 2. Pulse test,  $t \le 300\mu s$ , duty cycle,  $d \le 2\%$ .
- 3. Switching times & energy losses may increase for higher  $V_{CF}(Clamp)$ ,  $T_{J}$  or  $R_{G}$ .

#### **ADVANCE TECHNICAL INFORMATION**

The product presented herein is under development. The Technical Specifications offered are derived from a subjective evaluation of the design, based upon prior knowledge and experience, and constitute a "considered reflection" of the anticipated result. IXYS reserves the right to change limits, test conditions, and dimensions without notice.

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